

## Measurement of Gas Sensor Performance

- Gas sensing materials:

1. Sputtered ZnO film (150 nm)

(Massachusetts Institute of Technology)

2. Sputtered SnO<sub>2</sub> film (60 nm)

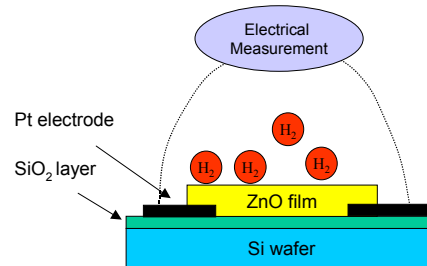
(Fraunhofer Institute of Physical Measurement Techniques)

- Target gases:

H<sub>2</sub>, CO, NH<sub>3</sub>, NO<sub>2</sub>, CH<sub>4</sub>

- Operating temperature:

320 - 460 °C



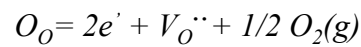
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## Mechanisms in Semiconducting Gas Sensor

- Bulk: Change in stoichiometry



→ Induce shallow donors: density related to PO<sub>2</sub>

$$n^2 [V_O^{\bullet\bullet}] PO_2^{1/2} = K_R(T) \Rightarrow n = (2 K_R(T))^{1/3} PO_2^{-1/6}$$

modulate



Bulk electronic conduction

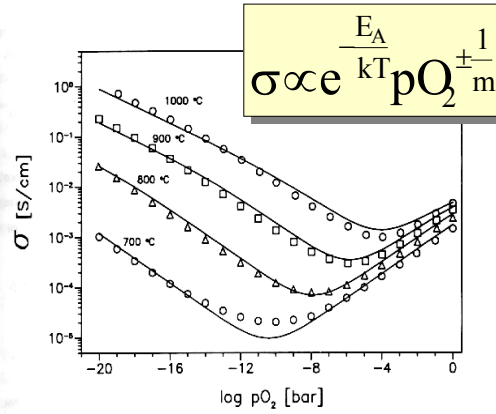
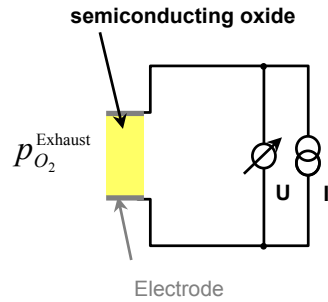


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## Resistive Oxygen Sensors Based on SrTiO<sub>3</sub>

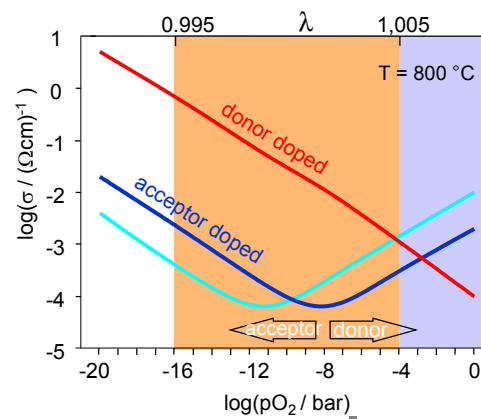


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## Influence of Dopants on Electrical Conductivity of SrTiO<sub>3</sub>



Acceptors: Al, Ni, Fe

Donors: Nb, Ta, Sb, Y, La, Ce, Pr, Nd, Pm, Sm, Gd

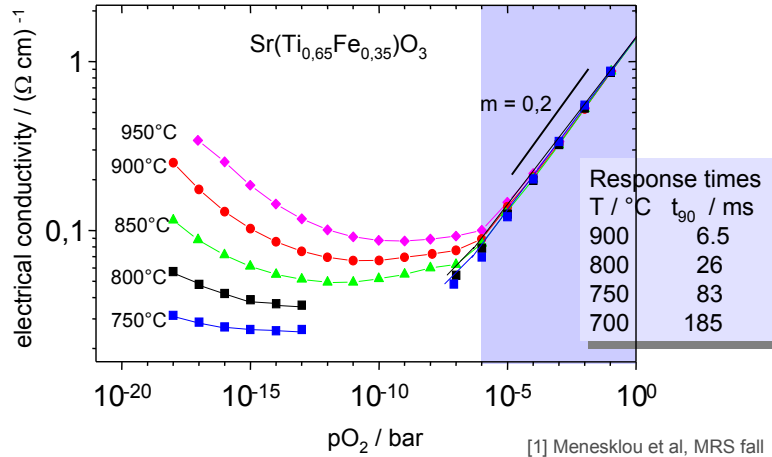


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## Temperature Independence: High Acceptor Concentration in SrTiO<sub>3</sub>



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## Oxygen Sensor in Thick Film Technology

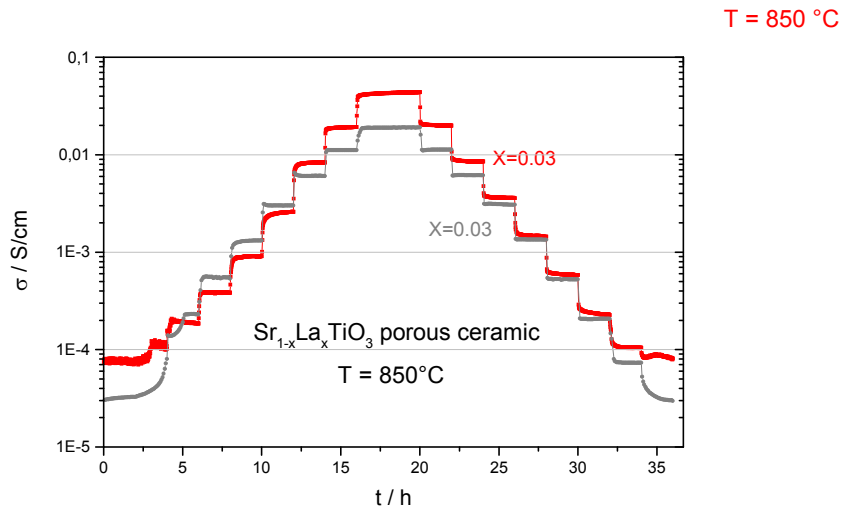


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## Transient Behavior of Porous $\text{Sr}_{1-x}\text{La}_x\text{TiO}_3$ for $x=0.005$ and $x=0.03$



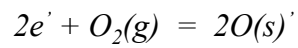
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## Mechanisms in Semiconducting Gas Sensor

### • Interface - Gas adsorption

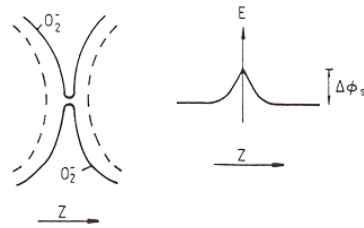


→ Induce space charge barrier

modulate

1. Surface conduction

2. Grain boundary barrier



Grain boundary barrier



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## Sensor Configuration



A single 9 mm<sup>2</sup> chip sensor array with:

- four sensing elements with interdigitated structure electrodes
- heater
- temperature sensor



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## Schematic Cross Section of Mounted Sensor



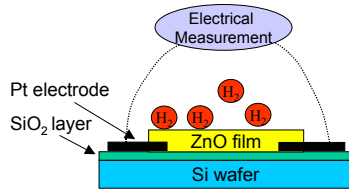
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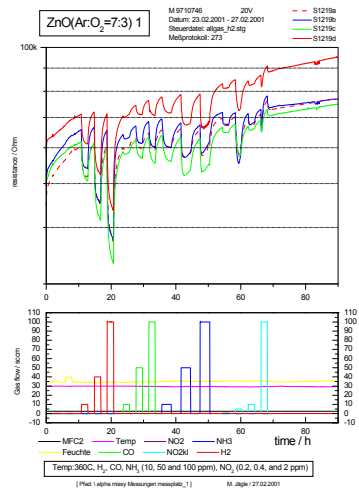
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# Resistance Response to Gas Environment

## Schematic of Gas Sensor Structure



- ZnO film (150 nm)
- Electrode: Pt(200 nm)/Ta(25 nm) film
- Insulation layer: SiO<sub>2</sub> layer (1 μm)
- Substrate: Si wafer



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# MicroElectroMechanical Systems - MEMS



Bulk Micromachining



Surface Micromachining

Micromachining - Application of microfabrication tools, e.g. lithography, thin film deposition, etching (dry, wet), bonding



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## Gas Sensors and MEMS

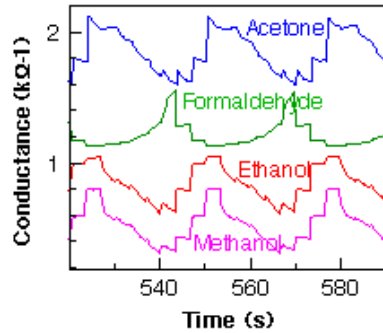
- Miniaturization
  - Reduced power consumption
  - Improved sensitivity
  - Decreased response time
  - Reduced cost
- Arrays
  - Improved selectivity
- Integration
  - Smart sensors



## Microhotplate



## Microhotplate Sensor Platform



### NIST Microhotplate Design



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## Microhotplate Characteristics

- Milli-second thermal rise and fall times
  - ➡ programmed thermal cycling
  - ➡ low duty cycle
- Low thermal mass
  - ➡ low power dissipation
- Arrays
  - ➡ enhanced selectivity



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## Harsh Environment MEMS

- High temperatures
  - Oxidation resistant
  - Chemically inert
  - Abrasion resistant
- Wide band gap semiconductor/insulator



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## Photo Electro-chemical Etching - PEC

### Features:

- *materials versatility e.g. Si, SiC, Ge, GaAs, GaN, etc.*
- *precise dimensional control down to 0.1 mm through the use of highly selective p-n junction etch-stops*
- *fabrication of structures with negligible internal stresses*
- *fabrication of structures not constrained by specific crystallographic orientations*



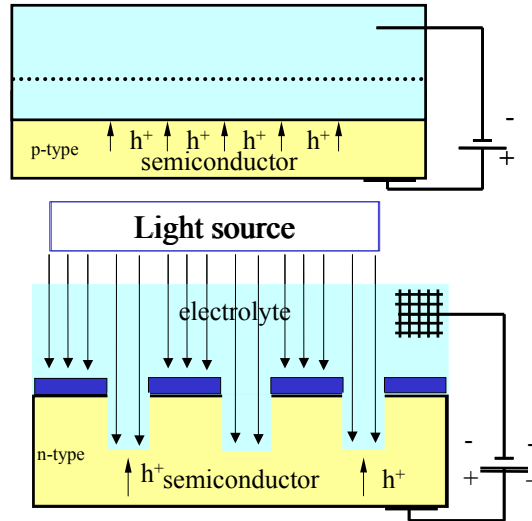
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## Photo Electro-chemical Etching - PEC

- Electro-chemical etching
- Photo electro-chemical etching



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## Examples ...

- Arrays of **stress free** 4.2  $\mu\text{m}$  thick cantilever beams.
- Photoelectrochemically micromachined cantilevers are **not constrained** to specific crystal planes or directions.
- Similar structures successfully micromachined from **SiC** by Boston MicroSystems personnel



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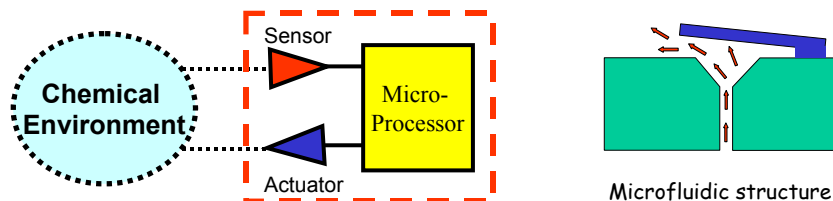
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## Smart Gas Sensor

### → *A Self Activated Microcantilever-based Gas Sensor*

1. A device capable of sensing a change in environment and responding without need for a microprocessor
2. A device has both gas sensing and actuating function by integration of semiconducting oxide and piezoelectric thin films.



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## Smart Gas Sensor

1. Semiconducting oxide thin films for high gas sensitivity  
: *Microstructure (Nano-Structure) and Composition*
2. Piezoelectric thin films for providing actuating function
3. Thin film electroceramic deposition methods for integrating with silicon microcantilever beam  
: *Compatibility with Si micromachining technology*
4. Microcantilever structures for the self activated gas sensor  
: *High performance in chemical environment*



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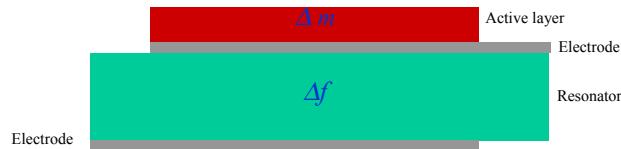
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## Resonant Gas Sensor

- Resonant Frequency:  $f_R = 1/2l (\mu_o/\rho_o)^{1/2}$   
 where  $l$  = resonator thickness,  $\mu_o$  = effective shear modulus and  $\rho_o$  = density
- Mass change causes shift in resonant frequency :  $(m_o - \Delta m) / m_o$   
 $\approx (f + \Delta f) / f$

Gas Sensor elements :

- (I) **Active layer** interacts with environment  
 - stoichiometry change translates into mass change
- (II) **Resonator** transduces mass change into resonance frequency change



## Choice of Piezoelectric Materials

- Temperature limitations of piezoelectric materials

Material	Max Operating Temperature (°C)	Limitations
Quartz	450	High loss
LiNbO <sub>3</sub>	300	Decomposition
Li <sub>2</sub> B <sub>4</sub> O <sub>7</sub>	500	Phase transformation
GaPO <sub>4</sub>	933 ?	Phase transformation
La <sub>2</sub> Ga <sub>5</sub> SiO <sub>4</sub> (Langasite)	1470 ?	Melting point



## Design Considerations

- **Bulk conductivity** dependent on temperature and  $PO_2$   
→ contributes to resonator electrical losses

**Modify bulk conductivity - how?**

- **Stability** to oxidation and reduction process  
→ limited oxygen non-stoichiometry  
→ slow oxygen diffusion kinetics

**Defect chemistry and diffusion kinetics study**

- $f_R(T)$ : Temperature dependence of resonant frequency  
→ need to differentiate from mass dependence

**Minimize @ intrinsic and device-levels**



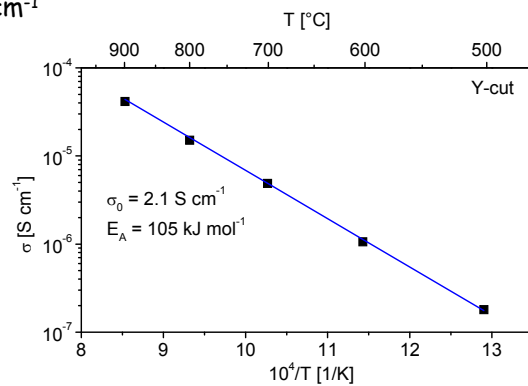
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## Langasite : Bulk Electrical Properties

- Single activation energy in the temperature range 500 - 900 °C
- Extrapolated room temperature conductivity:  $\sigma = 4.4 \times 10^{-18}$  S cm<sup>-1</sup>



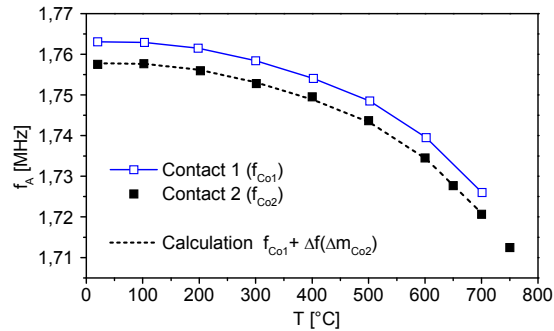
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## Langasite : $f_R(T)$

- Temperature dependence of the resonance frequency ( $f_R$ ) of a resonator device with difference mass loads.



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## Ongoing Activities

- **Resonator (Langasite) -- H. Seh & H. Fritze**
  - Defect chemistry
  - Oxygen diffusion/exchange studies
  - Bulk conductivity dependence on T and  $PO_2$
- **Active Layer (PCO) -- T. Stefanik**
  - Transport-Defect chemistry correlations
- **Gas Sensor --**
  - Add active layer (PCO) using PLD  $\Rightarrow$  nanocrystalline vs microcrystalline
  - Sensor testing



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